

LM800 Series Picomat II

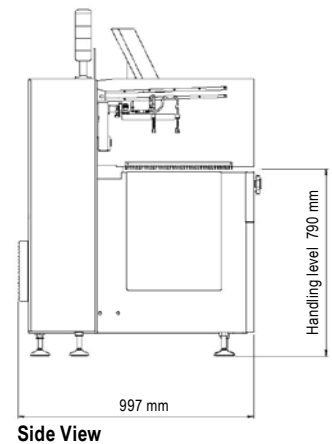
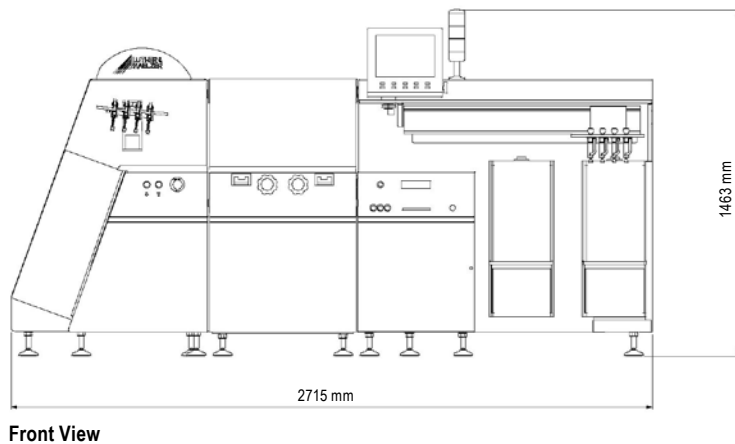
Octal-Density Grid Test System



- ▲ Extra High Density
- ▲ Accuracy
- ▲ Economical Efficiency
- ▲ Automatic Optical Alignment
- ▲ Low Ohm Testing

LM800 Picomat II Technical Specifications

Grid Test System



Test Field Size

Maximum (X x Y) 244 mm x 325 mm / 9.6" x 12.8"
(smaller field sizes available upon request)

Board Handling

Minimum board size (X x Y) 50 mm x 50 mm / 1.97" x 1.97"
Maximum board size (X x Y) 284 mm x 365 mm / 11.2" x 14.4"
Minimum board thickness
- manual testing 0.1 mm / 0.0039"
- automatic testing 0.6 mm / 0.023" and warpage < 10 mm
Maximum board thickness 8 mm / 0.315"

Test Points

35 mil (800 test points / inch²) one side / both sides
98,304 / 196,608

Test Parameters

Isolation test voltage 35 V to 250 VDC
15 V to 250 VDC
(optional, depending on test method)
Isolation threshold 100 kΩ to 100 MΩ
Continuity threshold 10 Ω to 10 kΩ
Embedded resistor measurement 1 Ω to 10 kΩ

Data Preparation

External generation of drill files, test files and object files for fault location is done in ADAM II

Required data formats for data preparation:

Gerber
Extended Gerber
IPC-D-356A
.dpf-data
ODB++
Mask & drill data

Fault Location

Fault location and verification is done in CAR II or on an atg flying prober

Options

- Retractable guide rails
- 4-wire measurement 10 mΩ to 100 Ω
- Board thickness control
- PCB offset detection module SNIPER including feedback frames

Power supply

AC 400 V [3 / N / PE AC 400 V] 50 / 60 Hz

Compressed air

Connecting pressure 6 bar

Temperature

20 °C to 25 °C

Relative humidity

40 % to 60 %

Machine weight

About 1000 kg / 2204 lbs

All information subject to change without notice!
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